



- ☒ (229) (((leadframe lead adj frame) )
- ☒ (382929) (lead, contact electrode) with insulat\$4
- ☒ (470) (stack\$4 near2 ((microchip micro adj chip chip integrat
- ☒ (50223) ((lead contact electrode) with insulat\$4) with cover\$
- ☒ (50) (stack\$4 near2 ((microchip micro adj chip chip integrat
- ☒ (7633) (((lead contact electrode) with insulat\$4) with cover\$
- ☒ (7) (stack\$4 near2 ((microchip micro adj chip chip integrat
- ☒ (88) (stack\$4 near2 ((microchip micro adj chip chip integrat
- ☒ (43) insulat\$4 near2 cover\$4 near4 exposed adj2 (contact el
- ☒ (828) insulat\$4 near4 exposed adj2 (contact electrode lead)
- ☒ (80) (prevent\$3 reduc\$3 eliminat\$3 minimiz\$3 suppress\$3 de
- ☒ (33) ((microchip micro adj chip chip integrated adj circuit di
- ☒ (3) "06177139"
- ☒ (229) (((leadframe lead adj frame) )

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DBs [USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM\_TDB

☒ Plurals

Default operator: OR

☒ Highlight all hit terms initially

(((leadframe lead adj frame)  
 ) with ((microchip micro adj chip chip integrated adj circuit die ic semiconductor adj (device element structure) )  
 ) with ((encapsula\$3 encapsulation mold\$3 resin)  
 )) and ((1 adj shaped) near2 (leadframe lead adj frame lead)  
 ))) (((stack\$4 near ((microchip micro adj chip chip integrated adj circuit die ic semiconductor adj (device element structure) ))) (stack\$4 near packag\$3)) and (((leadframe lead adj frame) with ((encapsula\$3 encapsulation mold\$3 resin) with ((microchip micro adj chip chip integrated adj circuit die ic semiconductor adj (device element structure) ))) and ((offset stagger\$3 shift\$3 zigzag\$4 align\$4 near2 angle pitch oblique\$4 inclin\$4 displac\$3)))

April 2003

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|   | <input type="checkbox"/>            | <input type="checkbox"/>            | Inventor Δ               | Document ID       | Issue Date | Page | Title  | Current OR | Current XRef                 | Ret |
|---|-------------------------------------|-------------------------------------|--------------------------|-------------------|------------|------|--|------------|------------------------------|-----|
| 1 | <input checked="" type="checkbox"/> | <input checked="" type="checkbox"/> | Asada, Junichi et al.    | US 5665651 A      | 19970909   | 13   | Process for encapsulating a semiconductor device and lead frame  | 29/827     | 257/E21.504;<br>257/E23.042; |     |
| 2 | <input type="checkbox"/>            | <input checked="" type="checkbox"/> | Fujimoto, Hiroaki et al. | US 6498393 B2     | 20021224   | 34   | Semiconductor device and method for the fabrication thereof  | 257/692    | 257/666;<br>257/787;         |     |
| 3 | <input checked="" type="checkbox"/> | <input checked="" type="checkbox"/> | Honuchi, Michio et al.   | US 20020031867 A1 | 20020314   | 17   | Semiconductor device and process of production of same   | 438/125    |                              |     |
| 4 | <input checked="" type="checkbox"/> | <input checked="" type="checkbox"/> | Huang, Chien Ping        | US 20020027273 A1 | 20020307   | 12   | Semiconductor package and fabricating method thereof   | 257/678    | 438/106                      |     |
| 5 | <input type="checkbox"/>            | <input type="checkbox"/>            |                          | JP 2000077598 A   | 20000314   | 7    | Lead frame structure of resin sealed semiconductor package e.g. chip size package, has protruding portion of L-shaped lead frame acting as |            |                              |     |
| 6 | <input type="checkbox"/>            | <input type="checkbox"/>            |                          | JP 11340373 A     | 19991210   | 3    | Thin small sized resin sealed electronic circuit chip has L-shaped metal lead frame with larger shape than chip and is depressed from op.  |            |                              |     |
| 7 | <input checked="" type="checkbox"/> | <input type="checkbox"/>            | Abe, Shunichi et al.     | US 20020105061 A1 | 20020808   | 33   | Semiconductor device and manufacturing method thereof  | 257/666    |                              |     |
| 8 | <input checked="" type="checkbox"/> | <input type="checkbox"/>            | Akizawa, Tetsuo et al.   | US 4483441 A      | 19841120   | 13   | Flat-type semiconductor device and packing thereof   | 206/716    | 206/499;<br>206/718          |     |